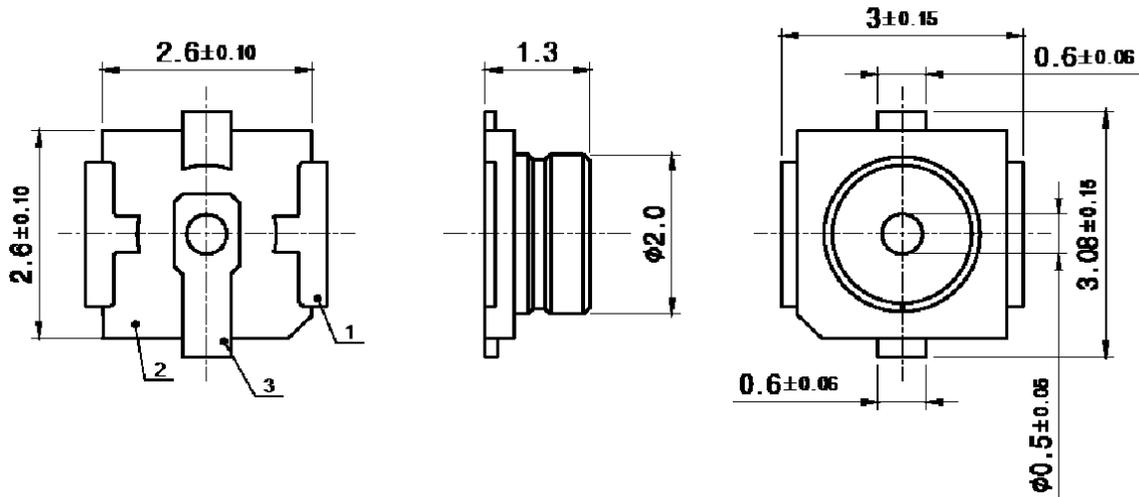
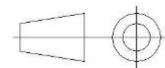


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- 1. MML-Body
- 2. MML-Insulator
- 3. MML-Signal Pin

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	<b>BRONZE</b>	<b>GOLD</b>
Center contact	<b>BRASS</b>	<b>GOLD</b>
Outer contact		
Insulator	<b>LCP</b>	
Gasket		
Others parts		
-	-	-
-	-	-

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**PACKAGING**

Standard	Unit	Other
<b>5000</b>	<b>Contact us</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

Impedance		<b>50</b>	$\Omega$
Frequency		<b>0-6</b>	GHz
VSWR	<b>1.35</b>	<b>+</b>	<b>0</b> x F(GHz) Maxi
Insertion loss		<b>NA</b>	$\sqrt{F}$ (GHz) dB Maxi
RF leakage		<b>NA</b>	- F(GHz) dB Maxi
Voltage rating		<b>60</b>	Veff Maxi
Dielectric withstanding voltage		<b>200</b>	Veff mini
Insulation resistance		<b>500</b>	M $\Omega$ mini

**ENVIRONMENTAL**

Operating temperature	<b>-40/+90</b>	$^{\circ}\text{C}$
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**MECHANICAL CHARACTERISTICS**

Center contact retention			
Axial force – Mating End		<b>NA</b>	N mini
Axial force – Opposite end		<b>NA</b>	N mini
Torque		<b>NA</b>	N.cm mini
Recommended torque			
Mating		<b>NA</b>	N.cm
Panel nut		<b>NA</b>	N.cm
Mating life		<b>30</b>	Cycles mini
Weight		<b>0.02</b>	g

**SPECIFICATION**

**OTHER CHARACTERISTICS**

Assembly instruction:

Others:

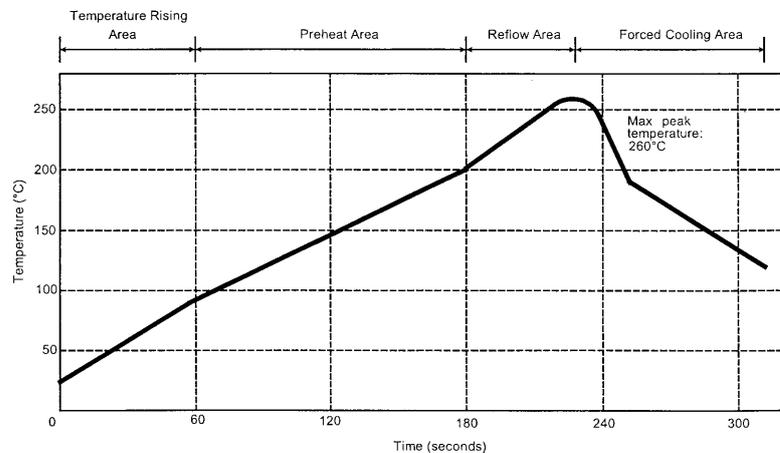
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### SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

**NOTE :** The receptacle and the plug must not be mated before completion of this procedure

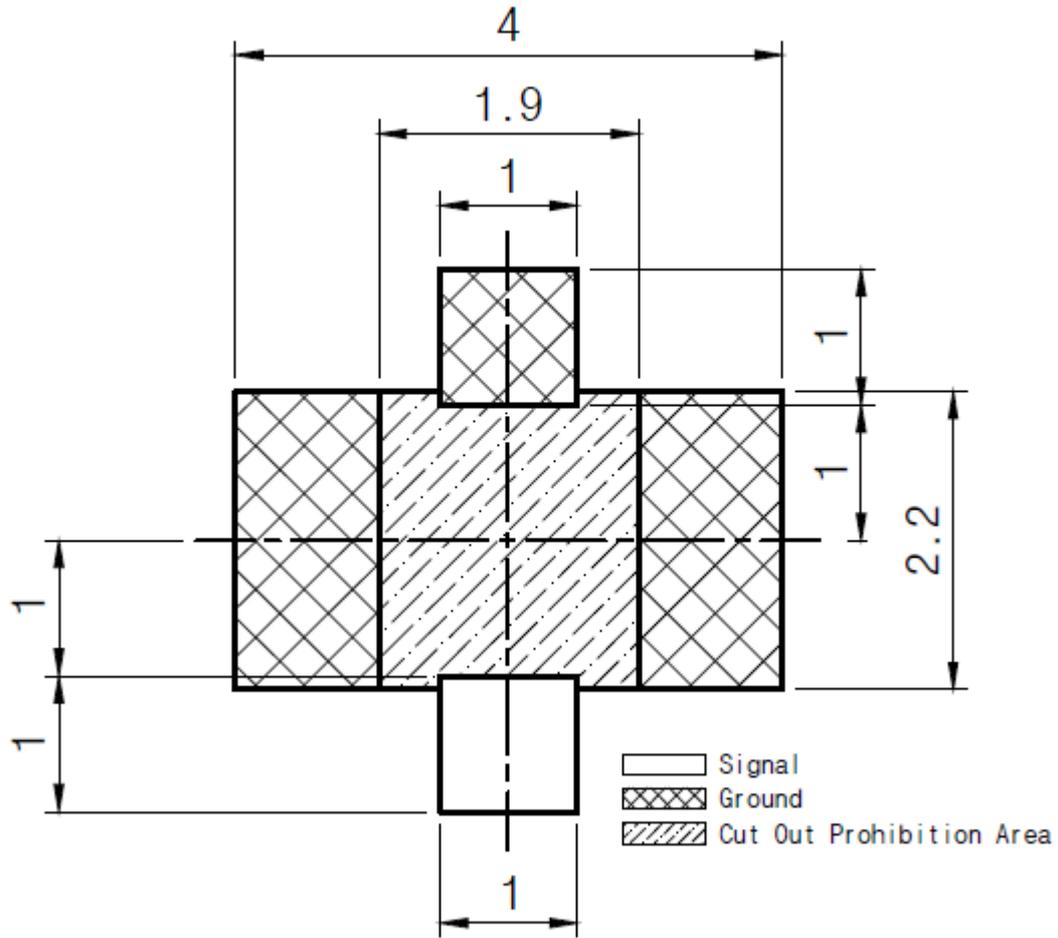
### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

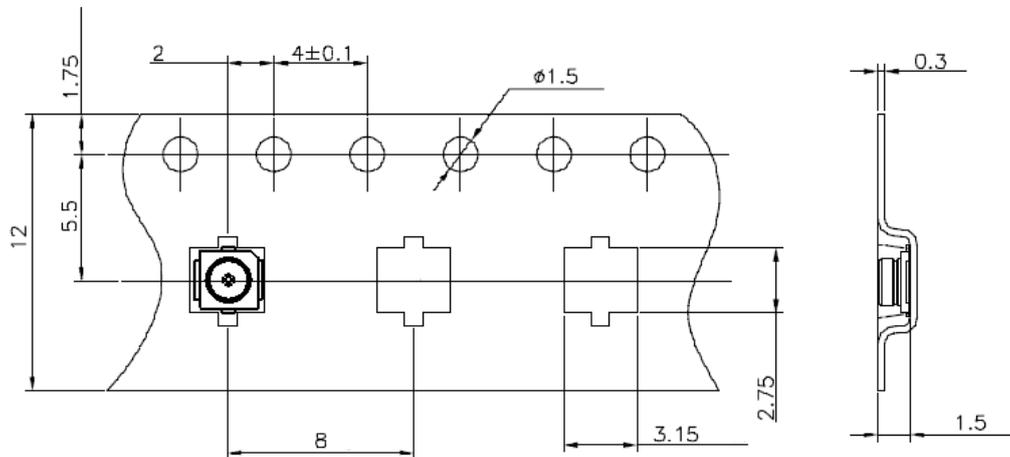
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### RECOMMENDED PCB DIMENSIONS



Tolerance:  $\pm 0.05\text{mm}$

### PACKING Embossed Taping



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Reel

